

Product Specification

850Gb/s OSFP Passive Direct Attach Copper Cable

P/N: NDR-OSFP-CU

Features

- Hot Pluggable OSFP form factor
- Wire AWG:30AWG,26AWG
- Available length range 0.5m~2.5m
- Operating data rate 850Gbps
- Power supply: +3.3V
- Max power dissipation <0.1W
- Based on 8-channels of 100G-PAM4 modulation
- Commercial temperature range 0°C to 70°C

Compliance

- Compliant with OSFP MSA
- Compliant with CMIS 5.1
- RoHS

Applications

- Supports 800Gb InfiniBand NDR Systems
- Cloud Services
- Data Center Interconnect
- Data center Enterprise networking
- Switches with OSFP ports



Description

The NDR-OSFP-CU is a high-performance, passive direct attach copper (DAC) cable designed to support InfiniBand NDR 800Gbps data transmission. Utilizing the OSFP module, this cable offers a cost-effective and energy-efficient solution for short-distance, high-speed interconnections within data centers and high-performance computing environments. Its passive design eliminates the need for additional power, reducing both operational costs and potential points of failure.

Ideal for connecting NVIDIA Quantum-2 InfiniBand switches, the NDR-OSFP-CU cable ensures seamless data flow with minimal latency. Its robust construction and compliance with industry standards make it suitable for dense network configurations, supporting the demanding requirements of artificial intelligence, scientific research, and large-scale cloud data centers. By leveraging this DAC cable, organizations can achieve high-bandwidth, low-latency connections essential for modern data-intensive applications.

Product performance Specifications

1. Basic Product Characteristics

| Parameter | Symbol | Min | Тур. | Мах | Unit |
|----------------------------|--------|-------|------|-------|------|
| Storage Temperature | Ts | -40 | - | +85 | °C |
| Supply Voltage | Vcc | -0.5 | 3.3 | 4.0 | V |
| Relative Humidity | RH | 5 | - | 85 | % |
| Operating Case Temperature | тс | 0 | - | 70 | °C |
| Power Supply Voltage | Vcc | 3.135 | 3.3 | 3.465 | V |
| Power Dissipation | PD | - | - | 0.1 | W |

2. High Speed Characteristics

| Parameter | Symbol | Min | Тур. | Мах | Unit | Condition |
|---|-------------------------------------|--|---|-------------------------|---------------|---------------|
| Resistance | Rcon | | | 3 | Ω | |
| Insulation Resistance | Rins | | | 10 | MΩ | |
| Raw cable impedance | Zca | 95 | | 110 | Ω | |
| Mated connector Impedance | Zmated | 85 | | 110 | Ω | |
| Maximum insertion Loss at 26.56 GHz | SDD21 | 11 | | 18 0.5M | dB | |
| | 30021 | 0.5 | | 19.75 1.0M 25.3 2.0M | uВ | |
| Differential to common-mode return loss | SCD11/ 22 | $\operatorname{RLcd}(f) \ge \begin{cases} 22 - 10(f/26.56) & 0.05 \le f < 26.56 \\ 15 - 3(f/26.56) & 26.56 \le f \le 40 \end{cases}$ | | | | 0.05 to 40GHz |
| Differential to common-mode conversion loss | SCD21- $(10, 0.05 \le f \le 12.89)$ | | $0.05 \le f < 12.89$ 08f $12.89 \le f \le 40^{-5}$ | dB | 0.05 to 40GHz | |



| Common-mode to common-mode return loss | SCC11/ 22 | | RLCC ≥18 | dB | 0.05 to 40GHz |
|--|--------------|---|----------|----|---------------|
| Minimum COM | COM | 3 | | dB | |

3. Product Optical and Electrical Characteristics

| Test Type | Test Item | 24AWG | 26AWG | 28AWG | 30AWG |
|-----------------------------|--|---|---|---|--|
| | Differential impedance | 100±5Ω at TDR | 100±5Ω | 100±5Ω | 100±5Ω at TDR |
| | Mutual capacitance | 14pF/ft nominal | 14pF/ft nominal | 14pF/ft nominal | 14pF/ft nominal |
| | Time delay | 1.31ns/ft nominal, (4.3ns/m) nominal | 1.35ns/ft nominal | 1.35ns/ft nominal | 1.35ns/ft nominal, (4.3ns/m) nominal |
| Electrical | Time delay skew (within pairs) | 80ps/10m maximum | 120ps/8.5m maximum | 120ps/7m maximum | 50ps/5.5m maximum |
| Characteristics | Time delay skew (between pairs) | 350ps/10m maximum | 500ps/8.5m maximum | 500ps/7m maximum | 350ps/5.5m maximum |
| | Attenuation | 10dB/10m maximum at 1.25Ghz | 10dB/8.5m maximum at 1.25Ghz | 10dB/7m maximum at 1.25Ghz | 8.4dB/5.5m maximum at 1.25Ghz |
| | Conductor DC Resistance | 0.026Ω /ft maximum at 20°C | 0.04Ω /ft maximum at 20°C | 0.06Ω/ft maximum at 20°C | 0.01Ω/ft maximum at 20°C |
| | Conductors (two pair) | 24AWG Solid, Silver plated copper | 26AWG Solid, Silver plated copper | 28AWG Solid, Silver plated copper | 30AWG Solid, Silver plated copper |
| | Insulation | Foam polyolefin | Foam polyolefin | Foam polyolefin | Foam polyolefin |
| | Pair drain wire | 26AWG Solid, Silver plated copper | 28AWG Solid, Silver plated copper | 30AWG Solid, Silver plated copper | 30AWG Solid, Silver plated copper |
| Physical Characteristics | Overall cable shield | Aluminum/polyester tape, 125% coverage, Tin plated copper braid, 38AWG, 85% coverage | Aluminum/polyester tape, 125% coverage, Tin plated copper braid, 38AWG, 85% coverage | Aluminum/polyest er tape, 125% coverage,Tin plated copper braid, 38AWG, 85% coverage | Aluminum/polyester tape, 125% coverage,Tin plated copper braid, 38AWG, 85% coverage |
| | Outer diameter | 6.0mm | 5.2mm | 4.7mm | 4.2mm |



Recommended Host Board Power Supply Circuit

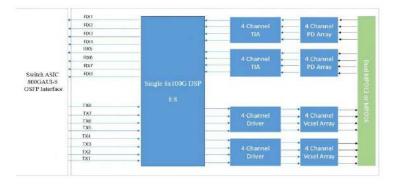


Figure 1: Module Block Diagram

Recommended Interface Circuit

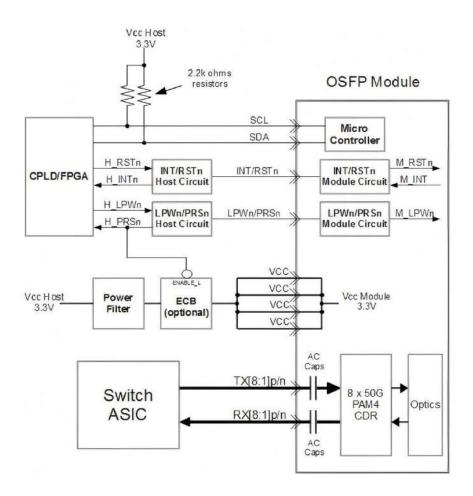


Figure2:Recommended Interface Circuit



Pin-out Definition

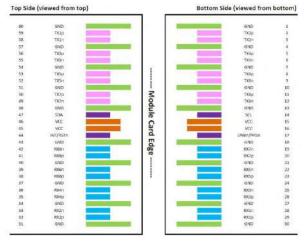


Figure3:Pin view

Pin Function Definitions

| Pin | Logic | Symbol | Description | Note | |
|-----|-------------|-----------|---------------------------------|------|--|
| 1 | | GND | Ground | | |
| 2 | CML-I | TX2p | Transmitter Data Non-Inverted | | |
| 3 | CML-I | TX2n | Transmitter Data Inverted | | |
| 4 | | GND | Ground | | |
| 5 | CML-I | TX4p | Transmitter Data Non-Inverted | | |
| 6 | CML-I | TX4n | Transmitter Data Inverted | | |
| 7 | | GND | Ground | | |
| 8 | CML-I | TX6p | Transmitter Data Non-Inverted | | |
| 9 | CML-I | TX6n | ransmitter Data Inverted | | |
| 10 | | GND | Ground | | |
| 11 | CML-I | TX8p | Transmitter Data Non-Inverted | | |
| 12 | CML-I | TX8n | Transmitter Data Inverted | | |
| 13 | | GND | Ground | | |
| 14 | LVCMOS-I/O | SCL | 2-wire Serial interface clock | 1 | |
| 15 | | VCC | +3.3V Power | | |
| 16 | | VCC | +3.3V Power | | |
| 17 | Multi-Level | LPWn/PRSn | Low-Power Mode / Module Present | 2 | |
| 18 | | GND | Ground | | |
| 19 | CML-O | RX7n | Receiver Data Inverted | | |
| 20 | CML-O | RX7p | Receiver Data Non-Inverted | | |



| 21 | | GND | Ground | |
|----|-------------|----------|---------------------------------|---|
| 22 | CML-O | RX5n | Receiver Data Inverted | |
| 23 | CML-O | RX5p | Receiver Data Non-Inverted | |
| 24 | | GND | Ground | |
| 25 | CML-O | RX3n | Receiver Data Inverted | |
| 26 | CML-O | RX3p | Receiver Data Non-Inverted | |
| 27 | | GND | Ground | |
| 28 | CML-O | RX1n | Receiver Data Inverted | |
| 29 | CML-O | RX1p | Receiver Data Non-Inverted | |
| 30 | | GND | Ground | |
| 31 | | GND | Ground | |
| 32 | CML-O | RX2p | Receiver Data Non-Inverted | |
| 33 | CML-O | RX2n | Receiver Data Inverted | |
| 34 | | GND | Ground | |
| 35 | CML-O | RX4p | Receiver Data Non-Inverted | |
| 36 | CML-O | RX4n | Receiver Data Inverted | |
| 37 | | GND | Ground | |
| 38 | CML-O | RX6p | Receiver Data Non-Inverted | |
| 39 | CML-O | RX6n | Receiver Data Inverted | |
| 40 | | GND | Ground | |
| 41 | CML-O | RX8p | Receiver Data Non-Inverted | |
| 42 | CML-O | RX8n | Receiver Data Inverted | |
| 43 | | GND | Ground | |
| 44 | Multi-Level | INT/RSTn | Module Interrupt / Module Reset | 2 |
| 45 | | VCC | +3.3V Power | |
| 46 | | VCC | +3.3V Power | |
| 47 | LVCMOS-I/O | SDA | 2-wire Serial interface data | 1 |
| 48 | | GND | Ground | |
| 49 | CML-I | TX7n | Transmitter Data Inverted | |
| 50 | CML-I | TX7p | Transmitter Data Non-Inverted | |
| 51 | | GND | Ground | |
| 52 | CML-I | TX5n | Transmitter Data Inverted | |
| 53 | CML-I | TX5p | Transmitter Data Non-Inverted | |
| 54 | | GND | Ground | |
| 55 | CML-I | TX3n | Transmitter Data Inverted | |
| 56 | CML-I | TX3p | Transmitter Data Non-Inverted | |
| 57 | | GND | Ground | |
| 58 | CML-I | TX1n | Transmitter Data Inverted | |



| 59 | CML-I | TX1p | Transmitter Data Non-Inverted |
|----|-------|------|-------------------------------|
| 60 | | GND | Ground |

Note1: Open-Drain with pull up resistor on Host.

Note2: See pin description for required circuit.

Monitoring Specification

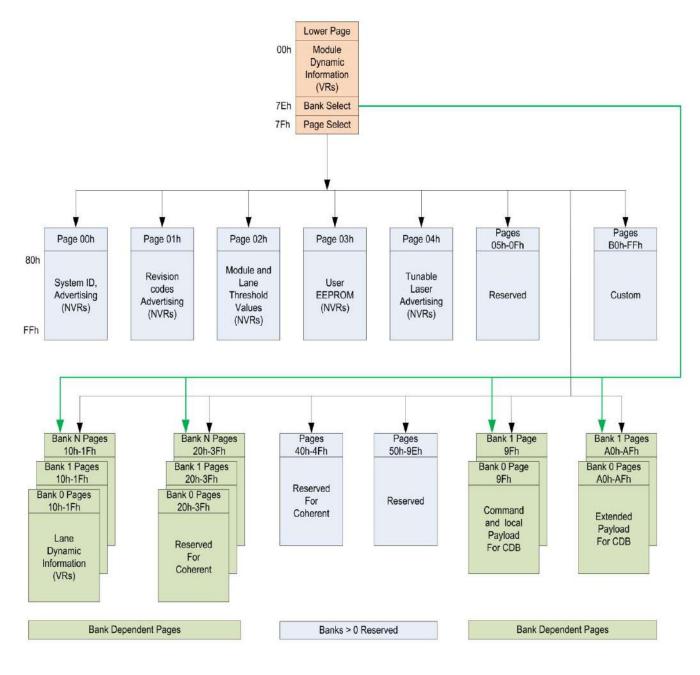


Figure4:Memory map



Memory map Table

| Byte | Unit | Name | Description |
|-------------|------|---------------------------|---|
| | | Lo | wer Page 00h |
| 0 | 1 | Identifier | Identifier - Type of Serial Module - See SFF-8024. |
| | | | Identifier – CMIS revision; the upper nibble is the whole number part |
| 1 | 1 | Revision Compliance | and the lower nibble is the decimal part. |
| | | | Example: 01h indicates version 0.1, 21h indicates version 2.1. |
| 2-3 | 2 | ID and Status Area | Flat mem indication, CLEI present indicator, Maximum TWI speed, |
| 4-7 | 4 | Lane Flag Summary | Current state of Module, Current state of the Interrupt signal. Flag summary of all lane flags on pages 10h-1Fh. |
| 4-7 8-13 | 6 | Module-Level Flags | All flags that are not lane or data path specific. |
| 14-25 | 12 | Module-Level Monitors | |
| | | Module-Level Monitors | Monitors that are not lane or data path specific. |
| 26-30 | 5 | | Controls applicable to the module as a whole |
| 31-36 | 6 | Module-Level Flag Masks | Masking bits for the Module-Level flags |
| 37-38 | 2 | CDB Status Area | Status of most recent CDB command |
| 39-40 | 2 | Module Firmware Version | Module Firmware Version. |
| 41-63 | 23 | Reserved Area | Reserved for future standardization |
| 64-82 | 19 | Custom Area | Vendor or module type specific use |
| 83-84 | 2 | Inactive Firmware Version | Version Number of Inactive Firmware. Values of 00h indicates module supports only a single image. |
| 85-117 | 33 | Application Advertising | Combinations of host and media interfaces that are supported by module data path(s) |
| 118-125 | 8 | Password Entry and Change | Password Entry and Change |
| 126 | 1 | Bank Select Byte | Bank address of currently visible Page |
| 127 | 1 | Page Select Byte | Page address of currently visible Page |
| | | Up | per Page 00h |
| 128 | 1 | Identifier | Identifier - Type of Serial Module - See SFF-8024. |
| 129-144 | 16 | Vendor name | Vendor name (ASCII) |
| 145-147 | 2 | Vendor OUI | Vendor IEEE company ID |
| 148-163 | 16 | Vendor PN | Part number provided by vendor (ASCII) |
| 164-165 | 8 | Vendor rev | Revision level for part number provided by vendor (ASCII) |
| 166-181 | 10 | Vendor SN | Vendor Serial Number (ASCII) |
| 182-183 | 2 | Date code year | ASCII code, two low order digits of year (00=2000) |
| 184-185 | 2 | Date code month | ASCII code digits of month (01=Jan through 12=Dec) |
| 186-187 | 2 | Date code day of month | ASCII code day of month (01-31) |
| 188-189 | 2 | Lot code | ASCII code, custom lot code, may be blank |
| 190-199 | 10 | CLEI code | Common Language Equipment Identification code |

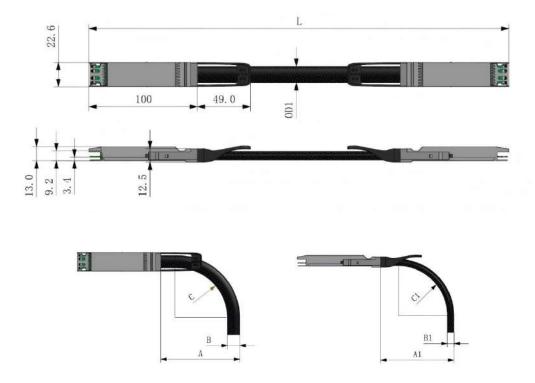
OSFP NDR Passive Direct Attach Copper Cable



| 200-201 | 2 | Module power characteristics | Module power characteristics |
|---------|----|------------------------------------|---|
| 202 | 1 | Cable assembly length | Cable assembly length |
| 203 | 1 | Media Connector Type | Media Connector Type |
| 204 | 1 | 5 GHz attenuation | Passive copper cable attenuation at 5 GHz in 1 dB increments |
| 205 | 1 | 7 GHz attenuation | Passive copper cable attenuation at 7 GHz in 1 dB increments |
| 206 | 1 | 12.9 GHz attenuation | Passive copper cable attenuation at 12.9 GHz in 1 dB increments |
| 207 | 1 | 25.8 GHz attenuation | Passive copper cable attenuation at 25.8 GHz in 1 dB increments |
| 208-209 | 2 | Reserved | Reserved |
| 210-211 | 2 | Cable Assembly Lane Information | Cable Assembly Lane Information |
| 212 | 1 | Media Interface Technology | Media Interface Technology |
| 213-220 | 8 | Reserved | Reserved |
| 221 | 1 | Custom | Custom |
| 222 | 1 | Checksum | Includes bytes 128-221 |
| 223-255 | 33 | Custom Info NV | Custom Info NV |



Mechanical Dimension



Note:

- Unit: mm
- Tolerance: φ0.1mm if not shown
- Latch color: black
- When L≤2m, the tolerance is ±25mm, when L>2m, the tolerance is ±50mm

Waring:

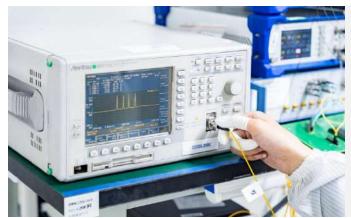
- The transceiver optics is supplied with a dust cover. This plug protects the transceiver optics during standard manufacturing processes by preventing contamination from air borne particles. It is recommended that the dust cover remain in the transceiver whenever an optical fiber connector is not inserted.
- Handling Precautions: This device is susceptible to damage as a result of electrostatic discharge (ESD). A static free environment is highly recommended. Follow guidelines according to proper ESD procedures.
- Laser Safety: Radiation emitted by laser devices can be dangerous to human eyes. Avoid eye exposure to direct or indirect radiation.



Test Center

1. Performance Testing

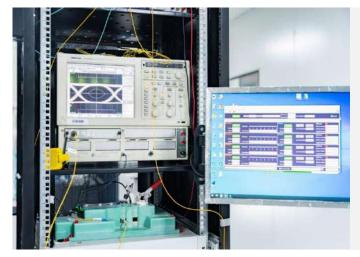
Every fiber optic transceiver is thoroughly tested by the LSOLINK Assurance Program, which is equipped with the world's most advanced analytical equipment to ensure that our transceivers meet the industry's international public protocol standards while still functioning flawlessly in your facility.



Optical Spectrum Inspection

Using the industry's leading optical spectrum analyser to check in real time that the parameters of the optical transceiver's laser comply with industry standards.

- Peak: Peak wavelength and peak level
- > 2nd Peak: Side-mode wavelength and level
- Mean WI: Center wavelength
- Total Power: Total power of spectrum
- SMSR: Side-Mode Suppression Ratio



Optical Signal Quality Inspection

Using highly efficient sampling oscilloscopes and BERT testers, equipped with an automated test platform to accurately test the signal quality of the transceiver, test records are kept for up to 5 years to ensure the traceability of each transceiver.

- Eye Mask Margin(NRZ)
- > TDECQ(PAM4):transmitter dispersion eye closure
- > OMA: Optical modulation amplitude
- BER: Bit error rate
- ER: Extinction Ratio



Flow Pressure Test

Using multi-protocol network traffic analyser with various brands of switches to test the transceiver's ability to transmit at full speed.

- **Bandwidth:** Actual transceiver bandwidth on the port
- Packet Loss
- Packet Errors:CRC Errors/PCS Errors/Symbol Errors
- LinkDown Counts
- > latency

Aboveis part of our test bed network equipment. For more information, Please click <u>download</u> for optical transceiver performance test report.



2. Quality Control

We adopt advanced quality management solutions. Each transceiver is self-inspected, including:20x microscope inspection, 200x microscope inspection, and QC process inspection.



visual inspection



Microscopic inspection: 20X



Microscopic inspection: 200X



Reliability Verification



Optical endface inspection



OQC Inspection



Order Information

| Part Number | Length(m) | Wire Gauge(AWG) | Connector Type | Cable Type | Cable Jacket |
|----------------|-----------|--------------------|----------------|----------------|--------------|
| NDR-OSFP-CU0.5 | 0.5 | 30 | OSFP to OSFP | Passive Copper | PVC |
| NDR-OSFP-CU1 | 1 | 26 | OSFP to OSFP | Passive Copper | PVC |
| NDR-OSFP-CU1.5 | 1.5 | 26 | OSFP to OSFP | Passive Copper | PVC |
| NDR-OSFP-CU2 | 2 | 26 | OSFP to OSFP | Passive Copper | PVC |
| NDR-OSFP-CU2.5 | 2.5 | 26 | OSFP to OSFP | Passive Copper | PVC |



Further Information

Lighting the Path to Global Links

- Web | www.lsolink.com
- Email | For Sales@lsolink.com

Disclaimer

- We are committed to continuous product improvement and feature upgrades, and the contents cont ained in this manual are subject to change without notice.
- 2. Nothing herein should be construed as constituting an additional warranty.
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